

## Surface Mount Devices: EU Directive Compliance Status by Product Type

Rev. O, 19 July 07

<u>Note</u>: Information deemd to be reliable for current manufacturing at the time of publication and is subject to change without notice. Monitor website regularly for updates. KEMET is not liable for any damages, direct or indirect, consequential or otherwise, that the reader might incur as a result of ignoring this warning, or that any third party might suffer as a result of the reader's ignoring this warning.

Туре	Product	Series Image	Series	Product Use	RoHS / ELV <sup>1</sup> Compliant Version Available	How to Order Product that	
						Meets RoHS Criteria	Does Not Meet RoHS Criteria
Multi- Layer Ceramic Surface Mount (SMD)	Standard, High Voltage, Tip & Ring		СххххС	Commercial	yes	'C' Suffix, e.g., C0805C104K5RA <u>C</u>	Option not available for 0201 products. 'L' Suffix, e.g., C0805C104K5RA <u>L</u>
	Open Mode		CxxxxF	Commercial	yes		
	KEMET Commercial-Off-The- Shelf (KCOTS)		СххххТ	Commercial or Military / Hi-Rel	yes		
	Low Profile Standard Chip		CxxxxL	Commercial	yes	'C' Suffix, e.g., C0805L475K9PA <u>C</u>	'L' Suffix, e.g., C0805L475K9PA <u>L</u>
	GR 900		CxxxxA	Hi-Rel	yes	SolderGuard II (tinned) = 'C' suffix.	SolderGuard I (solder-coated) = 'H' suffix.
	MIL-123 & KEMET Part Number Equivalents		CKS, CxxxxZ	Hi-Rel	yes	SolderGaurd II (tinned): MIL PN use 'W' or 'Y' suffix, KEMET PN use 'C' suffix.	SolderGuard I (solder-coated): MIL PN = 'S' suffix, KEMET PN = 'H' suffix.
	MIL-PRF-55681 & KEMET Part Number Equivalents		CDR, CxxxxP, CxxxxN	Military	yes	SolderGaurd II (tinned): MIL PN use 'W' or 'Y' suffix, KEMET PN use 'C' suffix.	SolderGuard I (solder-coated): MIL PN = 'S' or 'U' suffix, KEMET PN = 'H' suffix.
Tantalum Surface Mount (SMT)	Tantalum MnO₂		T491, T494, T495, T496, T497, T498, T499, T510	Commercial	yes	'T' Suffix for Matte Tin, e.g.,T491B105M035A <u>T</u> 'G' Suffix for Gold, e.g., T491B105M035A <u>G</u>	Must use 'H' Suffix, e.g., T491B105M035A <u>H</u>
	Tantalum MnO <sub>2</sub> per MIL-PRF-55365/8		T492 (CWR11)	Military / Hi-Rel	yes	For Gold termination, use 'G' Suffix, e.g., T492B105K035B <u>G</u>	For SnPb Termination, use 'S' suffix, e.g., T492B105K035B <u>S</u>
			T409 (CWR09), T419 (CWR19), T429 (CWR29)	Military / Hi-Rel	yes	Use 'B' Suffix for Gold Termination, e.g., T493D227M006C <u>B</u> , use 'T' Suffix for Tin Termination, e.g., T493D227M006C <u>T</u>	Solder option Termination Codes: 'H' = plated, 'C'= dipped, 'K' = Fused
	Tantalum Commercial-Off-The- Shelf (COTS)		T493	Hi-Rel	yes		
	Conductive Polymer		T520, T530	Commercial	yes	'T' Suffix <sup>1</sup> , e.g., T520V157M006A <u>T</u>	Must use 'H' Suffix, e.g., T520V157M006A <u>H</u>
	Face Down Termination Conductive Polymer		T528	Commercial	yes	Must use 'T' Suffix, e.g., T528Z337M2R5A <u>T</u>	No option - not available
	High Temp Condutive Polymer		T525	Commercial	yes	Must use 'T' Suffix, e.g., T525D337M006A <u>T</u>	Must use 'H' Suffix, e.g., T525D337M006A <u>H</u>
Aluminum Surface Mount			A700	Commercial	yes	Must use 'T' Suffix, e.g., A700V476M006A <u>T</u>	No option - not available
Inductors	Multi-Layer Chip Type	-	FBMH, FBMJ Series HK, LK, CK, BK, or BKP	Commerical	yes	Standard KEMET Part Number, e.g., FBMJ3216HL330TK	No option - not available
	Wound Chip Type		LB, LBMF, BC, CBMF, BRL, NR Series	Commercial	yes	Standard KEMET Part Number, e.g., NR4012T100MK	No option - not available

<sup>1</sup>Criteria for End of Life Vehicles (ELV) per EU Direction 2000/53/EC. Criteria for Restriction on the use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) per EU Directive 2002/95/EC as amended by 2005/618/EC requiring at the homogeneous level: 1000 PPM maximum content for Lead, Hexavalent Chromium, Mercury, PBD, and PBDE and 100 PPM maximum content for Cadmium, unless covered under exemption in Annex I.